

Silicon Schottky Diode

- General-purpose diode for high-speed switching
- Circuit protection
- Voltage clamping
- High-level detecting and mixing
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101¹⁾



BAS140W **BAS40-02L**



BAS40



BAS40-04



BAS40-05 **BAS40-05W**



BAS40-06 **BAS40-06W**



BAS40-07 **BAS40-07W**



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Package	Configuration	Marking
BAS140W	SOD323	single	white 4
BAS40	SOT23	single	43s
BAS40-02L *	TSLP-2-1	single, leadless	FF
BAS40-04	SOT23	series	44s
BAS40-05	SOT23	common cathode	45s
BAS40-05W	SOT323	common cathode	45s
BAS40-06	SOT23	common anode	46s
BAS40-06W	SOT323	common anode	46s
BAS40-07	SOT143	parallel pair	47s
BAS40-07W	SOT343	parallel pair	47s

¹* BAS40-02L is not qualified according AEC Q101

Maximum Ratings at $T_A = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	40	V
Forward current	I_F	120	mA
Non-repetitive peak surge forward current $t \leq 10\text{ms}$	I_{FSM}	200	
Total power dissipation BAS140W, $T_S \leq 113\text{°C}$ BAS40, BAS40-07, $T_S \leq 81\text{°C}$ BAS40-02L, $T_S \leq 127\text{°C}$ BAS40-04, BAS40-06, $T_S \leq 56\text{°C}$ BAS40-06W, $T_S \leq 106\text{°C}$ BAS40-05, $T_S \leq 31\text{°C}$ BAS40-05W, $T_S \leq 98\text{°C}$ BAS40-07W, $T_S \leq 118\text{°C}$	P_{tot}	250 250 250 250 250 250 250 250	mW
Junction temperature	T_j	150	°C
Operating temperature range	T_{op}	-55 ... 150	
Storage temperature	T_{stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BAS140W		≤ 150	
BAS40, BAS40-07		≤ 275	
BAS40-02L		≤ 90	
BAS40-04, BAS40-06		≤ 375	
BAS40-06W		≤ 175	
BAS40-05		≤ 475	
BAS40-05W		≤ 205	
BAS40-07W		≤ 125	

¹⁾For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

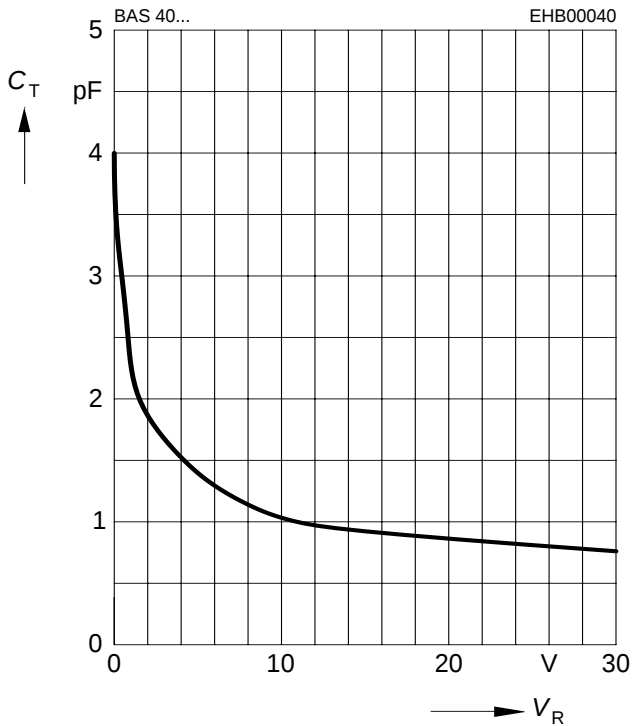
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Breakdown voltage $I_{(BR)} = 10 \mu A$	$V_{(BR)}$	40	-	-	V
Reverse current $V_R = 30 V$	I_R	-	-	1	μA
Forward voltage $I_F = 1 mA$ $I_F = 10 mA$ $I_F = 40 mA$	V_F	250 350 600	310 450 720	380 500 1000	mV
Forward voltage matching ¹⁾ $I_F = 10 mA$	ΔV_F	-	-	20	
AC Characteristics					
Diode capacitance $V_R = 0, f = 1 MHz$	C_T	-	3	5	pF
Differential forward resistance $I_F = 10 mA, f = 10 kHz$	R_F	-	10	-	Ω
Charge carrier life time $I_F = 25 mA$	τ_{rr}	-	-	100	ps

¹⁾ ΔV_F is the difference between lowest and highest V_F in a multiple diode component.

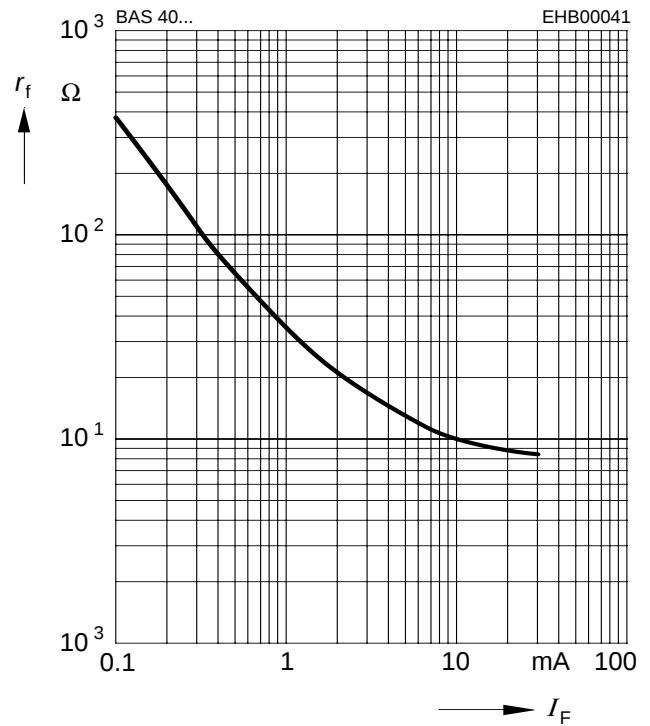
Diode capacitance $C_T = f(V_R)$

$f = 1\text{MHz}$



Forward resistance $r_f = f(I_F)$

$f = 10\text{ kHz}$



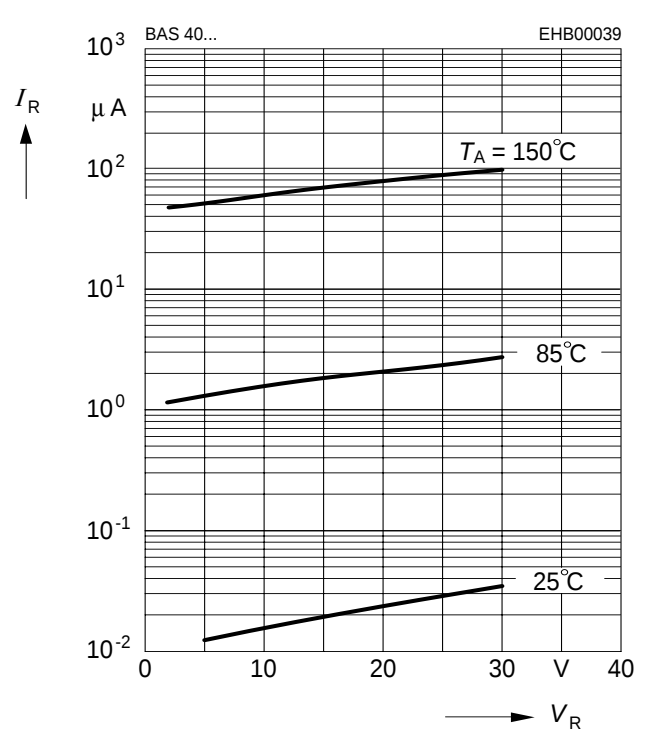
Reverse current $I_R = f(T_A)$

$V_R = \text{Parameter}$



Reverse current $I_R = f(V_R)$

$T_A = \text{Parameter}$



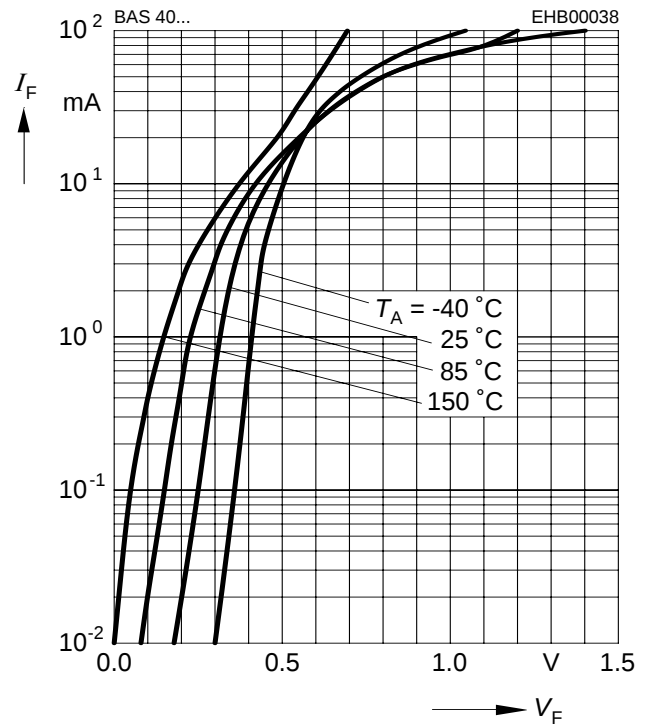
Forward Voltage $V_F = f(T_A)$

I_F = Parameter



Forward current $I_F = f(V_F)$

T_A = Parameter



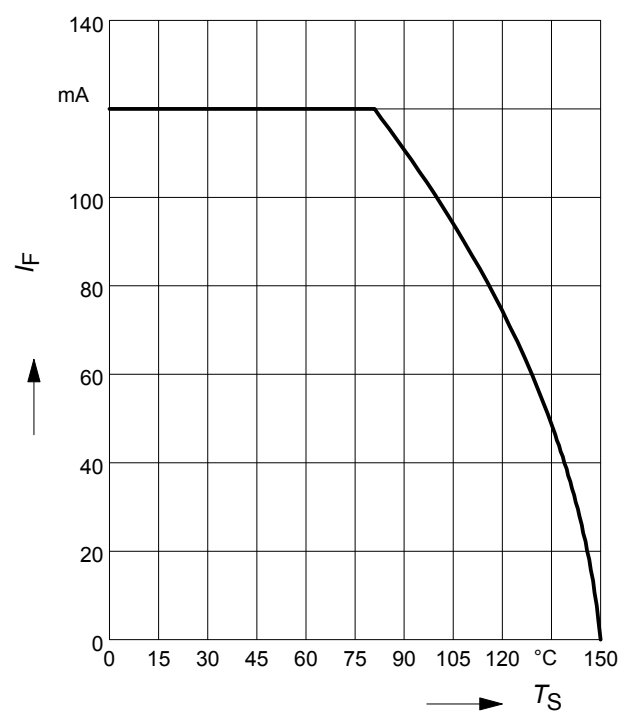
Forward current $I_F = f(T_S)$

BAS140W



Forward current $I_F = f(T_S)$

BAS40, BAS40-07



Forward current $I_F = f(T_S)$

BAS40-02L



Forward current $I_F = f(T_S)$

BAS40-04, BAS40-06



Forward current $I_F = f(T_S)$

BAS40-06W



Forward current $I_F = f(T_S)$

BAS40-05



Forward current $I_F = f(T_S)$
BAS40-05W

Forward current $I_F = f(T_S)$
BAS40-07W

Permissible Puls Load $R_{thJS} = f(t_p)$
BAS140W

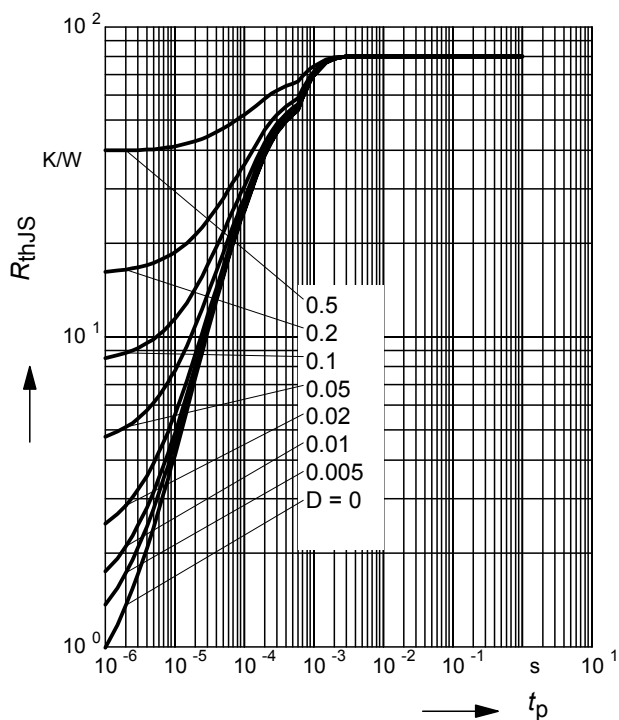
Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS140W


Permissible Puls Load $R_{thJS} = f(t_p)$

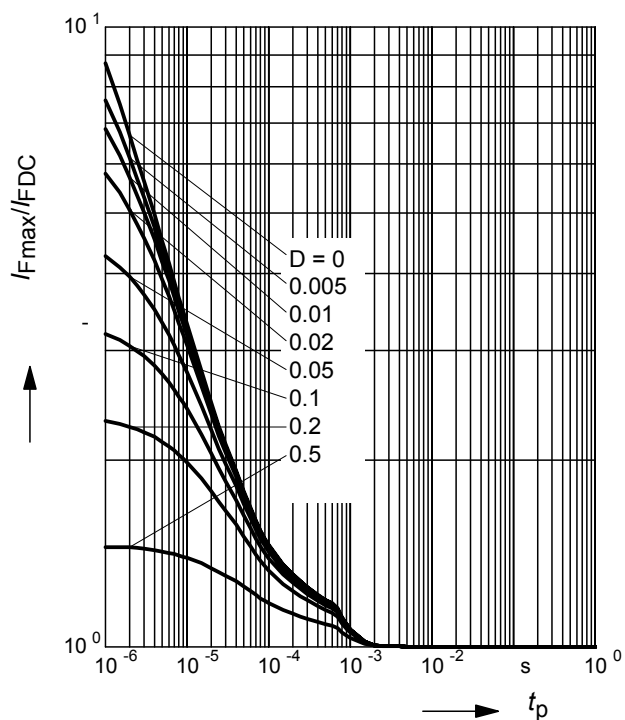
BAS40-02L



Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS40-02L



Permissible Puls Load $R_{thJS} = f(t_p)$

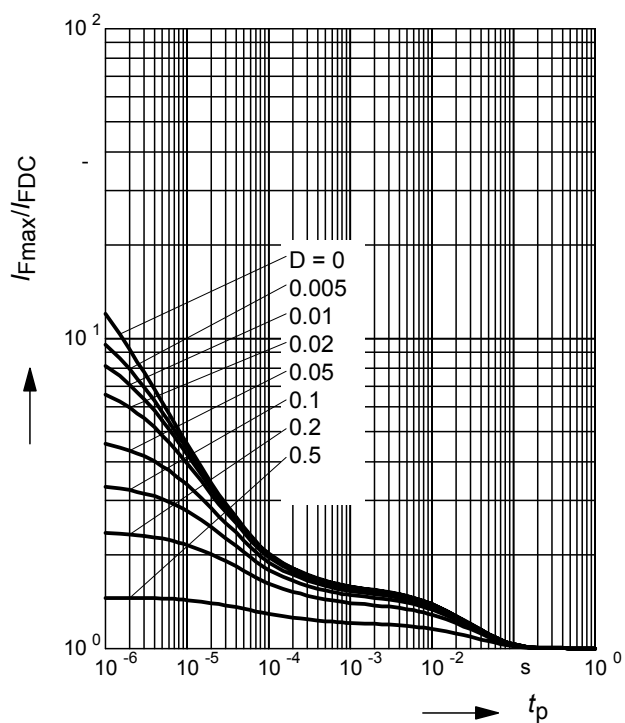
BAS40-06W



Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS40-06W



Permissible Puls Load $R_{thJS} = f(t_p)$

BAS40-05W



Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS40-05W



Package Outline



Foot Print



Marking Layout (Example)



Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



Package Outline



Foot Print



Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



Package Outline

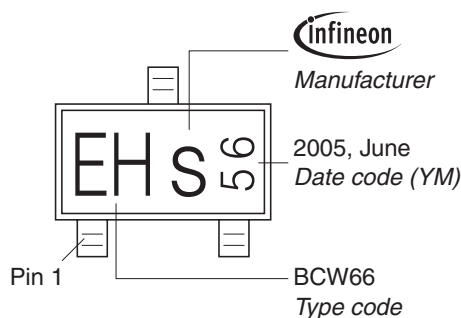


1) Lead width can be 0.6 max. in dambar area

Foot Print



Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



Package Outline



Foot Print



Marking Layout (Example)

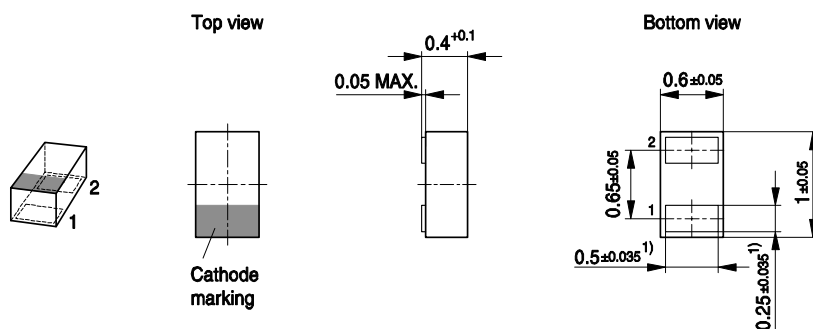


Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



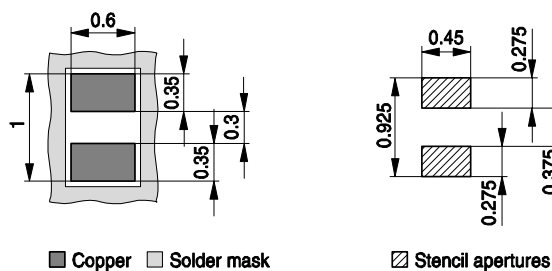
Package Outline



1) Dimension applies to plated terminal

Foot Print

For board assembly information please refer to Infineon website "Packages"



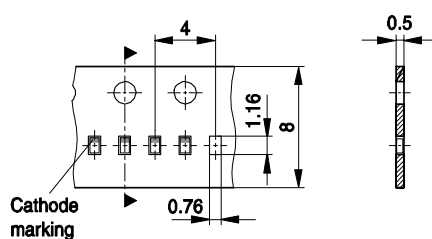
Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel

Reel ø330 mm = 50.000 Pieces/Reel (optional)



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